ABSTRACT

A semiconductor dynamic sensor such as an acceleration sensor is composed of a sensor chip having electrodes movable in response to acceleration applied thereto and a circuit chip having a circuit for processing signals fed from the sensor chip. The sensor chip and the circuit chip are contained and held in a packaging case. The sensor chip and the circuit chip are fixedly connected via an adhesive film. The sensor chip is correctly positioned on the circuit chip without creating misalignment relative to a sensing axis, because the adhesive film from which an adhesive material does not flow out under heat is used. A semiconductor wafer including plural sensor chips is first made and the adhesive film is stuck to one surface of the wafer, and then individual sensor chips are separated by dicing. The sensor chip is connected to the circuit chip via the adhesive film.